



Attorney Docket No.: 5649-553DV

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hyae-Ryoung Lee

Group Art Unit: 2815

Serial No.: 09/800,138

Examiner: Paul E. Brock II

Filed: March 6, 2001

Confirmation No.: 7287

For: METHODS OF FORMING INTEGRATED BONDING PADS INCLUDNIG
CLOSED VIAS AND CLOSED CONDUCTIVE PATTERNS

January 7, 2003

BOX NON-FEE AMENDMENT

Commissioner for Patents

Washington, DC 20231

AMENDMENT

Sir:

This Amendment is responsive to the Official Action of October 7, 2002. The claims have been amended herein using the rewritten claims format. The present amendment also includes a section entitled "**VERSION WITH MARKINGS TO SHOW CHANGES MADE**" attached hereto.

It is not believed that an extension of time and/or additional fee(s), including fees for additional claims, are required, beyond those that may otherwise be provided for in documents accompanying this paper. In the event, however, that an extension of time is necessary to allow consideration of this paper, such an extension is hereby petitioned under 37 C.F.R. §1.136(a). Any additional fees believed to be due in connection with this paper may be charged to our Deposit Account No. 50-0220.

In the Claims:

Please replace Claim 36 with the following like numbered claim:

36. (Twice Amended) A method according to Claim 35 wherein the step of forming the conductive pattern comprises the step of forming the conductive pattern filling the closed via and on the dielectric layer opposite the substrate.

Please cancel Claim 37 without prejudice or disclaimer.

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#11/E

1-29-03

L. Spruell

fee OK

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JAN 14 2003

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